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1	IS&R	L1	0	("component\$ and fiduci\$").PN.	USPAT; EPO; JPO; Derwent; IBM TDB	2001/02/11 17:04
2	IS&R	L7	0	("component\$ and fiducial").PN.	USPAT; EPO; JPO; Derwent; IBM TDB	2001/02/11 17:05
3	BRS	L13	1344	component\$ and fiducial	USPAT	2001/02/11 17:08
4	BRS	L14	269	component\$ same fiducial	USPAT	2001/02/11 17:09

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S PN = US 5894218
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UNITED STATES OF AMERICA (US)

Patent (No,Kind,Date): US 5894218 A 19990413
METHOD AND APPARATUS FOR AUTOMATICALLY POSITIONING ELECTRONIC DIE
WITHIN COMPONENT PACKAGES (English)

Patent Assignee: MICRON TECHNOLOGY INC (US)

Author (Inventor): FARNWORTH WARREN M (US); WOOD ALAN G (US);
JACOBSON JOHN O (US); HEMBREE DAVID R (US); WARK JAMES M (US);
FOLARON JENNIFER L (US); FOLARON ROBERT J (US); NELSON JAY C (US);
WARREN LELAN D (US)

Priority (No,Kind,Date): US 693398 A 19960807; US 228809 B2
19940418

Applic (No,Kind,Date): US 693398 A 19960807

National Class: * 324158100; 324754000

IPC: * G01R-031/02

Derwent WPI Acc No: * G 95-373964; G 99-263246; G 99-539638; G
01-089980; G 99-263246

Language of Document: English

Patent (No,Kind,Date): US 5955877 A 19990921
METHOD AND APPARATUS FOR AUTOMATICALLY POSITIONING ELECTRONIC DIE
WITHIN COMPONENT PACKAGES (English)

Patent Assignee: MICRON TECHNOLOGY INC (US)

Author (Inventor): FARNWORTH WARREN M (US); WOOD ALAN G (US);
JACOBSON JOHN O (US); HEMBREE DAVID R (US); WARK JAMES M (US);
FOLARON JENNIFER L (US); FOLARON ROBERT J (US); NELSON JAY C (US);
WARREN LELAN D (US)

Priority (No,Kind,Date): US 170844 A 19981013; US 693398 A3
19960807; US 228809 B2 19940418

Applic (No,Kind,Date): US 170844 A 19981013

Addnl Info: 5894218 Patented

National Class: * 324158100; 324765000

IPC: * G01R-031/26

Derwent WPI Acc No: * G 95-373964; G 99-263246; G 99-539638; G
01-089980; G 99-539638

Language of Document: English

Patent (No,Kind,Date): US 6064194 A 20000516

METHOD AND APPARATUS FOR AUTOMATICALLY POSITIONING ELECTRONIC DIE
WITHIN COMPONENT PACKAGES (English)

Patent Assignee: MICRON TECHNOLOGY INC (US)

Author (Inventor): FARNWORTH WARREN M (US); FOLARON JENNIFER L (US);
FOLARON ROBERT J (US); HEMBREE DAVID R (US); JACOBSON JOHN O (US);
NELSON JAY C (US); WARREN LELAN D (US)

Priority (No,Kind,Date): US 767700 A 19961217; US 228809 B1
19940418

Applic (No,Kind,Date): US 767700 A 19961217

National Class: * 324158100; 324765000

IPC: * G01R-031/02

Derwent WPI Acc No: * G 95-373964; G 99-263246; G 99-539638; G
01-089980

Language of Document: English

Patent (No,Kind,Date): US 6150828 A 20001121

METHOD AND APPARATUS FOR AUTOMATICALLY POSITIONING ELECTRONIC DIE WITH
COMPONENT PACKAGES (English)

Patent Assignee: MICRON TECHNOLOGY INC (US)

Author (Inventor): FARNWORTH WARREN M (US); WOOD ALAN G (US);
JACOBSON JOHN O (US); HEMBREE DAVID R (US); WARK JAMES M (US);
FOLARON JENNIFER L (US); FOLARON ROBERT J (US); NELSON JAY C (US);
WARREN LELAN D (US)

Priority (No,Kind,Date): US 400515 A 19990920; US 170844 A3
19981013; US 693398 A3 19960807; US 228809 B2 19940418

Applic (No,Kind,Date): US 400515 A 19990920

Addnl Info: 5955877 19990921 Patented; 5894218 19990413 Patented

National Class: * 324758000; 324158100

IPC: * B65G-049/07; G01R-031/26; H01L-021/66

Derwent WPI Acc No: * G 95-373964; G 99-263246; G 99-539638; G
01-089980; G 01-089980

Language of Document: English

Patent (No,Kind,Date): US 6210984 BA 20010403

METHOD AND APPARATUS FOR AUTOMATICALLY POSITIONING ELECTRONIC DIE
WITHIN COMPONENT PACKAGES (English)

Patent Assignee: MICRON TECHNOLOGY INC (US)

Author (Inventor): FARNWORTH WARREN M (US); WOOD ALAN G (US);
JACOBSON JOHN O (US); HEMBREE DAVID R (US); WARK JAMES M (US);
FOLARON JENNIFER L (US); FOLARON ROBERT J (US); NELSON JAY C (US);
WARREN LELAN D (US)

Priority (No,Kind,Date): US 399640 A 19990920; US 170844 A3
19981013; US 693398 A3 19960807; US 228809 B2 19940418

Applic (No,Kind,Date): US 399640 A 19990920

Addnl Info: 5955877 19990921 Patented; 5894218 19990413 Patented

National Class: * 438015000; 438017000; 438010000; 438012000

IPC: * H01L-021/66

Derwent WPI Acc No: * G 95-373964; G 99-263246; G 99-539638; G
01-089980

Language of Document: English

Patent (No,Kind,Date): US 6353312 BA 20020305

METHOD FOR POSITIONING A SEMICONDUCTOR DIE WITHIN A TEMPORARY PACKAGE
(English)

Patent Assignee: MICRON TECHNOLOGY INC (US)

Author (Inventor): FARNWORTH WARREN M (US); FOLARON JENNIFER L (US);
FOLARON ROBERT J (US); JACOBSON JOHN O (US); HEMBREE DAVID R (US);
NELSON JAY C (US); WARREN LELAN D (US)

Priority (No,Kind,Date): US 234226 A 19990120; US 767700 A3

19961217; US 228809 B1 19940418
Applic (No,Kind,Date): US 234226 A 19990120
Addnl Info: 6064194 Patented
National Class: * 324158100; 324765000; 324758000
IPC: * G01R-031/02
Derwent WPI Acc No: * G 95-373964; G 99-263246; G 99-539638; G
01-089980
Language of Document: English

UNITED STATES OF AMERICA (US)

Legal Status (No,Type,Date,Code,Text):

US 5894218	P	19940418	US AA	PRIORITY
			US 228809 B2	19940418
US 5894218	P	19960807	US AE	APPLICATION DATA (PATENT)
			(APPL. DATA (PATENT))	
			US 693398 A	19960807
US 5894218	P	19961007	US AS02	ASSIGNMENT OF ASSIGNOR'S
			INTEREST	
			MICRON TECHNOLOGY, INC.	8000 S. FEDERAL WAY
			BOISE, IDAHO 83706-963	; FOLARON, JENNIFER L.
			: 19960927; FOLARON, ROBERT J.	: 19960927;
			NELSON, JAY C. : 19960927;	WARREN, LELAN D. :
			19960927	
US 5894218	P	19990413	US A	PATENT
US 5894218	P	19991116	US CC	CERTIFICATE OF CORRECTION
US 5955877	P	19940418	US AA	PRIORITY
			US 228809 B2	19940418
US 5955877	P	19960807	US AA	PRIORITY
			US 693398 A3	19960807
US 5955877	P	19981013	US AE	APPLICATION DATA (PATENT)
			(APPL. DATA (PATENT))	
			US 170844 A	19981013
US 5955877	P	19990921	US A	PATENT
US 5955877	P	20010410	US CC	CERTIFICATE OF CORRECTION
US 6064194	P	19940418	US AA	PRIORITY
			US 228809 B1	19940418
US 6064194	P	19961217	US AE	APPLICATION DATA (PATENT)
			(APPL. DATA (PATENT))	
			US 767700 A	19961217
US 6064194	P	20000516	US A	PATENT
US 6064194	P	20011127	US CC	CERTIFICATE OF CORRECTION
US 6150828	P	19940418	US AA	PRIORITY
			US 228809 B2	19940418
US 6150828	P	19960807	US AA	PRIORITY
			US 693398 A3	19960807
US 6150828	P	19981013	US AA	PRIORITY
			US 170844 A3	19981013
US 6150828	P	19990920	US AE	APPLICATION DATA (PATENT)
			(APPL. DATA (PATENT))	
			US 400515 A	19990920
US 6150828	P	20001121	US A	PATENT
US 6210984	P	19940418	US AA	PRIORITY
			US 228809 B2	19940418
US 6210984	P	19960807	US AA	PRIORITY (DIVISION)
			US 693398 A3	19960807
US 6210984	P	19981013	US AA	PRIORITY (DIVISION)

US 170844 A3 19981013
US 6210984 P 19990920 US AE APPLICATION DATA (PATENT)
(APPL. DATA (PATENT))
US 399640 A 19990920
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PRE-GRANT PUBLICATION)
US 6353312 P 19940418 US AA PRIORITY
US 228809 B1 19940418
US 6353312 P 19961217 US AA PRIORITY (DIVISION)
US 767700 A3 19961217
US 6353312 P 19990120 US AE APPLICATION DATA (PATENT)
(APPL. DATA (PATENT))
US 234226 A 19990120
US 6353312 P 20020305 US BA PATENT (NO PREVIOUS
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